

岱煒科技股份有限公司
ASSEM TECHNOLOGY CO.,LTD.
SPECIFICATION FOR APPROVAL

PART NAME : 0.4PH 0.8H Ultra-Slim BTB Connector

ASE5BXX10 (Socket)

PART NO. : ASE6BXX10(Header)

APP. DATE : 2016.11.22

MANUFACTURER SIGNATURE

TABLE OF CONTENT

- I. SPECIFICATION OF PRODUCT
- II. MATERIAL REFERENCE TABLE
- III. MATERIAL CERTIFICATE OF HOUSING
- IV. MATERIAL CERTIFICATE OF TERMINAL
- V. ENGINEERING DRAWING OF PRODUCT

PRODUCT NAME: 0.4mm pitch mating height 0.8mm Ultra-Slim Board-to-Board Connector

REV: A

ISSUE DATE: 2011-11-01

PAGE: 1

ASSEM TECHNOLOGY 岱煒科技股份有限公司

SPECIFICATION OF PRODUCT

0.4mm pitch mating height 0.8mm Ultra-Slim Board-to-Board Connector

1. Scope:

This specification covers the requirements of product performance, and test methods provisions of 0.4mm pitch mating height 0.8mm Ultra-Slim Board-to-Board connector.

2. Applicable documents:

The following document from a part of this specification to the extent specified herein. In the event of conflict between the requirements of this specification and the product drawing, the product drawing shall take precedence. In the event of conflict between the requirements of this specification and the referenced documents, this specification shall take precedence.

3. Requirements:

3.1. Materials:

Contact: Copper Alloy. Gold Plating.

Housing: Heat Resistance Plastic.

4. Manufacture Place :

No.17, Minquan ST., Tucheng Dist., New Taipei City 23679, TAIWAN

5. Electrical Performance:

No.	Items	Requirements	Test Procedures
5.1	Rated current	0.3A per pin (All pins can carry Max.5A)	-
5.2	Rated voltage	30V AC/DC	-
5.3	Breakdown Voltage	150V AC for 1minute (Initial stage)	In accordance with method of JIS C5402. Test with 1mA current and 250VDC for 1 minute
5.4	Insulation resistance	1000MΩ Min.(initial)	
5.5	Contact resistance	80mΩ Max.	

PRODUCT NAME: 0.4mm pitch mating height 0.8mm Ultra-Slim Board-to-Board Connector

REV: A

ISSUE DATE: 2011-11-01

PAGE: 2

ASSEM TECHNOLOGY 岱煒科技股份有限公司

6. Environmental Performance:

No.	Items	Requirements	Test Procedures
6.1	Ambient Temperature	-55°C ~ 85°C	No freezing or condensation
6.2	Storage Temperature	-55°C ~ 85°C ..(Products only) -40°C ~ 50°C (Packaging structure)	No freezing or condensation
6.3	Thermal shock	5 cycles Contact resistance.80mΩ Max Insulation resistance 100MΩ Min.	In accordance with method MIL-STD-202G method 107G. -55±3°C (30min) → 25±3°C (5min) → 85±3°C (30min) → 25±3°C (5min) → -55±3°C (30min) for 5 cycles.
6.4	Humidity	Contact resistance.80mΩ Max Insulation resistance 100MΩ Min.	In accordance with MIL-STD-1344A method 1002 The specimens shall be placed in a chamber and subjected to a relative humidity of 90 to 95 % and temperature of 40±2°C for 120 hours
6.5	Salt spray	Contact resistance.80mΩ Max Insulation resistance 100MΩ Min.	In accordance with method MIL-STD-1344A method 1001. The specimens subjected to the chamber temperature of 35±2°C exposure to a salt spray from 5±1% solution for 24 hours.
6.6	H ₂ S resistance	Contact resistance.80mΩ Max	Bath temperature 40±2°C Gas concentration 3±1ppm Humidity 75 to 80%R.H. for 48hours.

PRODUCT NAME: 0.4mm pitch mating height 0.8mm Ultra-Slim Board-to-Board Connector

REV: A

ISSUE DATE: 2011-11-01

PAGE: 3

ASSEM TECHNOLOGY 岱煒科技股份有限公司

7. Mechanical Performance:

No.	Items	Requirements	Test Procedures
7.1	Insertion force	1.2Nf. max. per pin	Mate applicable header or socket at the speed of 5±1 mm/min.
7.2	Withdrawal force	0.2Nf. min. per pin	Mate applicable header or socket at the speed of 5±1 mm/min.
7.3	Vibration	Appearance no damage, loose part nor crack. Contact Resistance :80mΩMAX. Discontinuity : 1μs MAX.	In accordance with method MIL-STD-202G method 201 condition A, all contacts shall be connected in series and DC 5mA shall be applied. Wave form : Sine wave. Frequency :10~55~10Hz/1min. Amplitude : 1.5mm. Orientation : X,Y,Z (3 axes). Duration : 2hrs./axis.
7.4	Shock	Appearance no damage, loose part nor crack. Contact Resistance :80mΩMAX. Discontinuity : 1μs MAX.	In accordance with method MIL-STD-202G method 213B condition A. DC 100mA shall be applied. MAX acceleration: 50G. Wave form : Half sine wave. Orientation : X,Y,Z (3 axes). Duration : 11ms./axis. Times: 3 times/axis.
7.5	Resistance to soldering heat	No loose contacts nor damage	1. Hand soldering: Soldering time: 3 ± 0.5 second. Solder temperature: 350 ± 5°C. 2. Reflow: In accordance with method MIL-STD-202 method 210 condition K.
7.6	Durability	.. Contact Resistance :80mΩMAX.	Mate applicable header or socket , insert and withdrawal at the speed rate of 5 ± 1 mm/min. up to 50 times

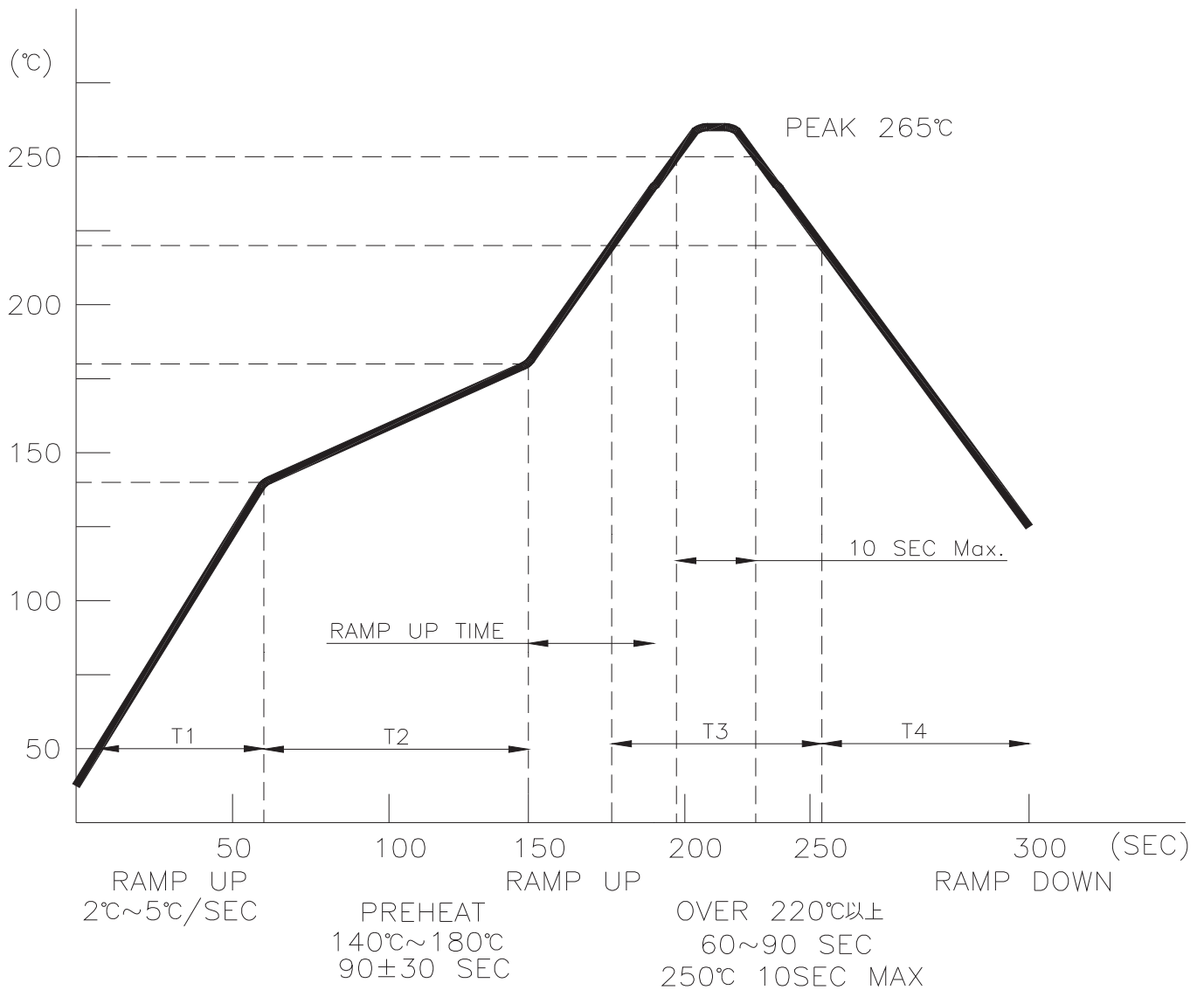
PRODUCT NAME: 0.4mm pitch mating height 0.8mm Ultra-Slim Board-to-Board Connector

REV: A

ISSUE DATE: 2011-11-01

PAGE: 4

8. RECOMMENDED IR REFLOW PROFILE



T1:	Temperature Ramp Up Rate	2°C~5°C/SEC
T2:	Preheat: 140°C~180°C	90±30 SEC
T3:	Time Over 220°C	60~90 SEC
T4:	Ramp Down Rate During Cooling	4°C~7°C/SEC
	Peak Temperature	265°C Max

PRODUCT NAME: 0.4mm pitch mating height 0.8mm Ultra-Slim Board-to-Board Connector

REV: A

ISSUE DATE: 2011-11-01

PAGE: 5

ASSEM TECHNOLOGY 岱煒科技股份有限公司

II. MATERIAL REFERENCE TABLE

Parts Name	General Name	Model No.	Heat Resistance Level	UL Card No.
Housing	LCP	E471i(d)	UL94V-0	E106764
Socket Terminal	Phosphor Borne	C5210R-EH	—	—
Header Terminal	Phosphor Borne	C5191-EH	---	---

PRODUCT NAME: 0.4mm pitch mating height 0.8mm Ultra-Slim Board-to-Board Connector

REV: A

ISSUE DATE: 2011-11-01

PAGE: 6

ASSEM TECHNOLOGY 岱煒科技股份有限公司

III. MATERIAL CERTIFICATE OF HOUSING

General Properties of E471i

table1-1 General Properties (ISO)

Item	Unit	Test Method	Standard, For SMT
			E471i
			Low warpage, Standard
Color			VF2201/BK210P
ISO(JIS)quality-of-the-material display:		ISO11469 (JIS K6999)	>LCP-(GF+MD)35<
Density	g/cm ³	ISO 1183	1.67
Water absorption (23°C,24hrs)	%	ISO 62	0.03
Tensile strength	MPa	ASTM D638	140
Tensile elongation	%	ASTM D638	2.3
Flexural strength	MPa	ISO 178	195
Flexural modulus	MPa	ISO 178	13,500
Flexural strain	%	ISO 178	2.5
Charpy impact strength (notched)	kJ/m ²	ISO 179/1eA	20
Temperature of deflection under load (1.8MPa)	°C	ISO 75-1,2	265
Temperature of deflection under load (0.45MPa)	°C	ISO 75-1,2	285
Dielectric breakdown strength (1mmt)	kV/mm	IEC 60243-1	47
Dielectric breakdown strength (3mmt)	kV/mm	IEC 60243-1	25
Volume resistivity	Ω·cm	IEC 60093	2 × 10 ¹⁶
Volume resistivity (Our standard)	Ω·cm		-
Relative permittivity (1kHz)		IEC 60250	4.3
Relative permittivity (1MHz)		IEC 60250	3.8
Dielectric dissipation factor (1kHz)		IEC 60250	0.02
Dielectric dissipation factor (1MHz)		IEC 60250	0.03
Tracking resistance (CTI)	V	IEC 60112	150
Arc resistance	s		176
Mold Shrinkage (80×80×1mmt, Flow direction, Inj. pressure 60MPa)	%	Our standard	0.06
Mold Shrinkage (80×80×1mmt, Trans-direction, Inj. pressure60MPa)	%	Our standard	0.43
Mold Shrinkage (80×80×1mmt, Flow direction, Inj. pressure79MPa)	%	Our standard	-
Mold Shrinkage (80×80×1mmt, Trans direction, Inj pressure 79MPa)	%	Our standard	-
Rockwell hardness	M(Scale)	ISO2039-2	65
Flammability		UL94	V-0
The yellow card File No.			E106764
Appropriate List number of Ministerial Ordinance for Export Trade Control			Item 16 of Appendix -1

All figures in the table are the typical values of the material and not the minimum values of the material specifications.

PRODUCT NAME: 0.4mm pitch mating height 0.8mm Ultra-Slim Board-to-Board Connector

REV: A

ISSUE DATE: 2011-11-01

PAGE: 7

ASSEM TECHNOLOGY 岱焯科技股份有限公司

I. E471i的一般物性

表 1-1 一般物性(ISO)

项 目	单 位	试验方法	高耐热, 高流动
			E471i
			低翘曲性
密度	g/cm ³	ISO 1183	1.67
拉伸强度*	MPa	ASTM D638	140
拉伸率*	%	ASTM D638	2.3
弯曲强度	MPa	ISO 178	195
弯曲模量	MPa	ISO 178	13500
弯曲应变	%	ISO 178	2.5
简支梁冲击强度(有缺口)	kJ/m ²	ISO 179/1eA	20
负荷变形温度(1.8MPa)	°C	ISO 75-1,2	265
成型收缩率(80×1mmt, 流动方向, 注射压力60MPa)	%		0.06
成型收缩率(80×1mmt, 垂直方向, 注射压力60MPa)	%		0.43
成型收缩率(80×1mmt, 流动方向, 注射压力79MPa)	%		-
成型收缩率(80×1mmt, 垂直方向, 注射压力79MPa)	%		-
体积电阻率	Ω · cm	IEC 60093	1.0×10 ¹⁶
表面电阻率	Ω	IEC 60093	1.0×10 ¹⁶
介电常数(1kHz)		IEC 60250	4.3
介电常数(1MHz)		IEC 60250	3.8
介电常数(10GHz)			3.7
介电损耗角正切(1kHz)		IEC 60250	0.018
介电损耗角正切(1MHz)		IEC 60250	0.032
介电损耗角正切(10GHz)			0.007
绝缘破坏强度(1mmt)	kV/mm	IEC 60243-1	47
绝缘破坏强度(3mmt)	kV/mm	IEC 60243-1	25
耐导电径迹	CTI	IEC 60112	150
耐电弧性	s		176
阻燃性		UL94	V-0

以上数值为材料的代表性测试值、并非该规格材料的最低值。

*1)有关UL (Underwriters Laboratories Inc.) 的认定值、请参照UL发行的黄卡 (File No.E106764)。

*2)本品级受以日本国外汇管理及外国贸易法为依据的出口贸易管理条例表中的第1条第16项的制约。

PRODUCT NAME: 0.4mm pitch mating height 0.8mm Ultra-Slim Board-to-Board Connector

REV: A

ISSUE DATE: 2011-11-01

PAGE: 8

ASSEM TECHNOLOGY 岱煒科技股份有限公司

Component - Plastics

E106764

POLYPLASTICS CO LTD

VECTRA DIV, 18-1 KONAN 2-CHOME, MINATO-KU, TOKYO 108-8280 JP

E471i(d)

Liquid Crystal Polymer (LCP), "VECTRA", furnished as pellets

Color	Min Thk (mm)	Flame Class	HWI	HAI	RTI Elec	RTI Imp	RTI Str
NC, BK	0.1	V-0	-	-	130	130	130
	0.8	V-0	-	-	130	130	130
ALL	1.5	V-0	-	-	130	130	130
	3.0	V-0	-	-	130	130	130

Comparative Tracking Index (CTI): **3**

Dimensional Stability (%): -

High-Voltage Arc Tracking Rate
(HVTR): -

High Volt, Low Current Arc Resis (D495): -

Dielectric Strength (kV/mm): -

Volume Resistivity (10^x ohm-cm): -

(d) - Virgin and regrind up to 50% by weight incl., have the same basic material characteristics in NC and BK with a minimum thickness of 0.80mm.

ANSI/UL 94 small-scale test data does not pertain to building materials, furnishings and related contents. ANSI/UL 94 small-scale test data is intended solely for determining the flammability of plastic materials used in the components and parts of end-product devices and appliances, where the acceptability of the combination is determined by UL.

Report Date: 2000-01-31

Last Revised: 2010-04-26

Underwriters Laboratories Inc®



PRODUCT NAME: 0.4mm pitch mating height 0.8mm Ultra-Slim Board-to-Board Connector		
REV: A	ISSUE DATE: 2011-11-01	PAGE: 9

ASSEM TECHNOLOGY 岱煒科技股份有限公司

MATERIAL CERTIFICATE OF SOCKET TERMINAL

P.002/003

(FAX)

2013/05/28 08:55 mono

試 験 成 績 書 INSPECTION CERTIFICATE

J X 日 敏 日 石 金 属 株 式 会 社 倉 見 工 場
KURAMI WORKS, JX NIPPON MINING & METALS CORPORATION

顧客
CUSTOMER
振 先 台湾日敏金属
MESSRS.
製品名 C5210R-EH (HP)
PRODUCTS
寸法 0.08 X 150Z X L
SIZE
規格
SPECIFICATION

発 行 日 2013年02月06日
DATE OF ISSUE
納 品 書 番 号 42984
DELIVERY SHEET NO.
注 文 番 号 TLC12-647
CONTRACT NO.
オ ー ダ ー 番 号 01
ORDER NO.

0005 神奈川県高座郡寒川町倉見3番地
3 KURAMI, SAMUKAWA-MACHI, KOBUZA-GUN,
KANAGAWA-KEN 〒253-0101
TEL. 0467-75-0611

品質保証課長
MANAGER OF QUALITY
ASSURANCE SECTION

Y. Ozeki

化学成分 CHEMICAL COMPOSITIONS

規格 SPECIFICATION	Zn %	Sn %	P %	Fe %	Pb %	Cu+Sn+P %								質量 MASS (KG)
製造番号 MIN	7.0	7.0	0.03			99.7								
LOT NO. MAX	0.20	9.0	0.35	0.10	0.02									
80347	0.01	7.68	0.12	0.001	0.002	99.90								1,234.00

機械的および物理的性質 MECHANICAL AND PHYSICAL PROPERTIES

規格 SPECIFICATION	引張強さ TENSILE STRENGTH N/mm ²	伸び: ASTM ELONGATION (ASTM) %	耐力 PROOF STRESS N/mm ²	硬さ HARDNESS HV	90°曲試験 90° BEND TEST (L)	90°曲試験 90° BEND TEST (T)							寸法検査 DIMENSIONAL INSPECTIONS	GOOD
製造番号 MIN	685	11.0	590	210									外観検査 SURFACE INSPECTIONS	GOOD
LOT NO. MAX	785			280	R=TX0.5	R=TX1.0							備考 REMARKS.	
80347	748	19.0	711	240	GOOD	GOOD								

この製品は品質管理計画に基づき製造され、検査・試験を行ない、規格に合格したことを証明する。
WE HEREBY CERTIFY THAT THE PRODUCTS DESCRIBED HEREIN HAVE BEEN MANUFACTURED, INSPECTED AND TESTED IN ACCORDANCE WITH THE SPECIFICATION AND Q. C. PROGRAM.

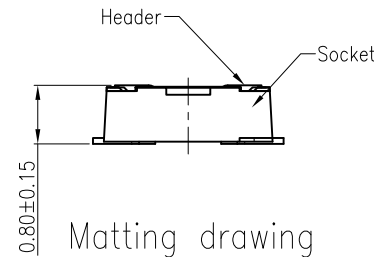
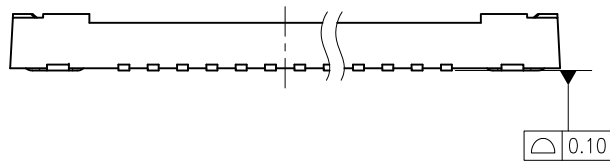
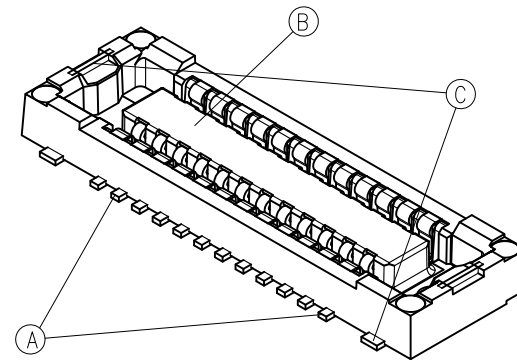
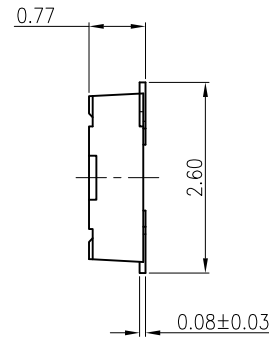
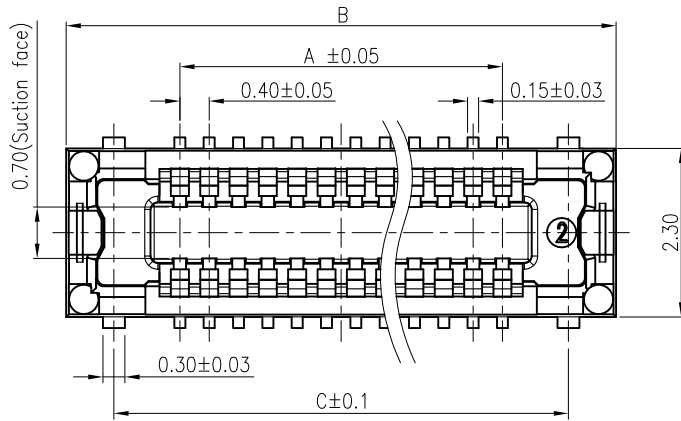
PRODUCT NAME: 0.4mm pitch mating height 0.8mm Ultra-Slim Board-to-Board Connector		
REV: A	ISSUE DATE: 2011-11-01	PAGE: 11

CUSTOMER

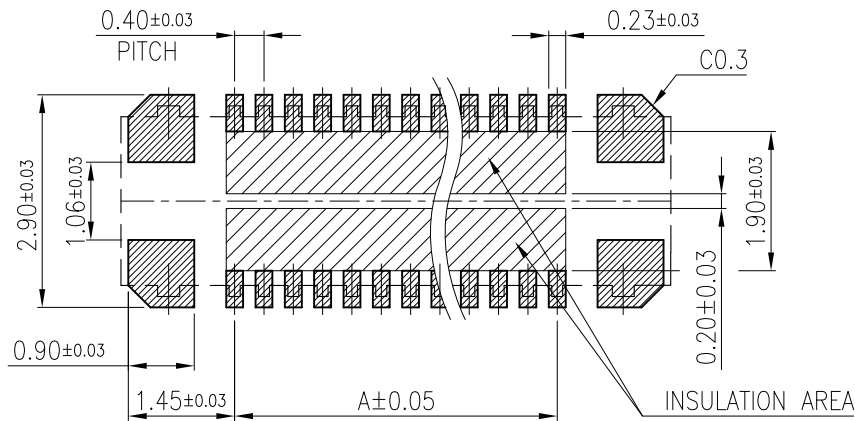
REV.	DCN/ECN	DESCRIPTION	DR.	DATE	APPD.

Dimension table (mm)

No. of contacts	Dimension		
	A	B	C
50	9.60	12.70	11.40
60	11.60	14.70	13.40
70	13.60	16.70	15.40



Matting drawing



Recommended PC board pattern (mounting pad layout)

NOTES :

1. Plating : Contact : Contact portion : Au plating (Min. 0.05 μ m) over nickel
Terminal portion : Au plating over nickel

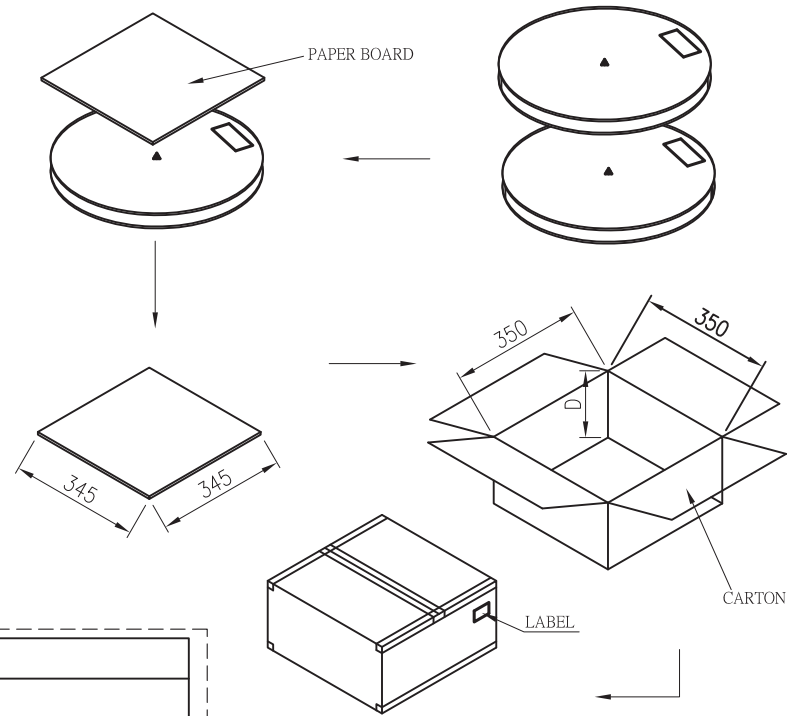
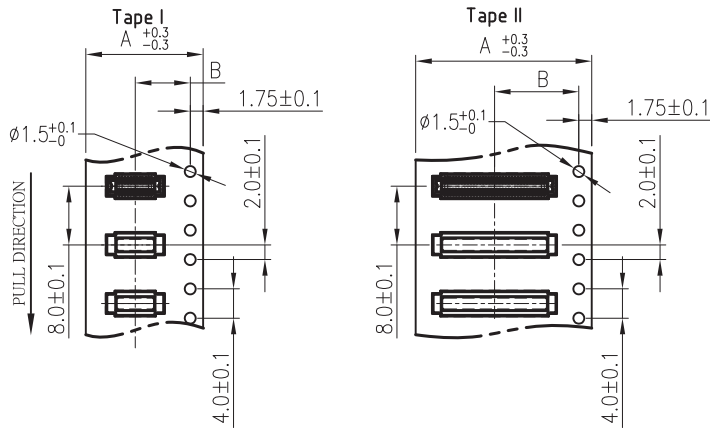
2. Part No. : ASE 5B XX 10

No. OF SERIES [] Contacts No.
5B : SOCKET WITH HOLDDOWN

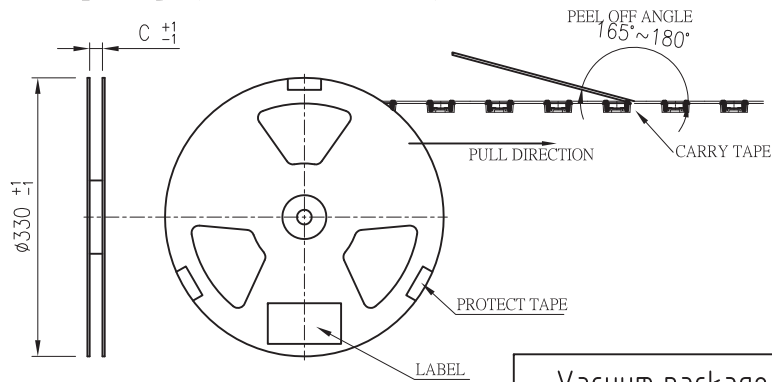
ITEM	DESCRIPTIONS	QTY.	MATERIAL	FINISH	REMARKS
(C)	HOLDDOWN	2	COPPER ALLOY	TIN	-
(B)	HOUSING	1	HIGH TEMP.PLASTIC	BLACK	UL94-V0
(A)	TERMINAL	-	COPPER ALLOY	GOLD	-

General tolerance		P/N	TITLE		REMARKS	
DIMENSION	ANGLES	ASE5BXX10	0.4mm Pitch BOARD TO BOARD MATED HEIGHT 0.80mm SOCKET CONNECTOR		D/N ASE5BXX10	
... ± 0.4	X° ± 5°	DR. PHIL	Original Date	2011/05/30	SCALE UNIT REV. SHEET	
.X ± 0.3	X.X° ± 3°	CHK. JERRY	1:1	mm	A	1/1
.XX ± 0.15		APPD. STING	ATC		ASSEM TECHNOLOGY CO., LTD.	
.XXX ± 0.1						

REV.	DCN/ECN	DESCRIPTION	DR.	DATE	APPD.



Reel package (EIAJ ET - 7200B) MATERIAL : PS



Vacuum package
 1. Vacuum the air out of the bag.
 2. Prevent the dust involve.

CARTON LABEL

Description	
Part No.	
Quantity	
N. W	
G. W	

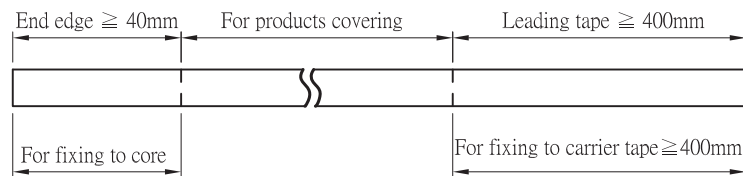
REEL LABEL

Assem Technology Co., Ltd

Description	
Part No.	
Quantity	
Date Code	

PIN	P / N	Type of taping	DIM A	DIM B	DIM C	Reel	Reels	Carton	DIM D
70	ASES700	Tape II	24.0	11.5	25.4	5	25000 pcs	180	
60	ASES600								
50	ASES500								
44	ASES440								
40	ASES400								
36	ASES360								
34	ASES340	Tape I	16.0	7.5	17.4	5	25000 pcs	145	
30	ASES300								
26	ASES260								
24	ASES240								
22	ASES220								
20	ASES200								
18	ASES180								
16	ASES160								
14	ASES140								
12	ASES120								
10	ASES100								

Cover Tape MATERIAL : PET

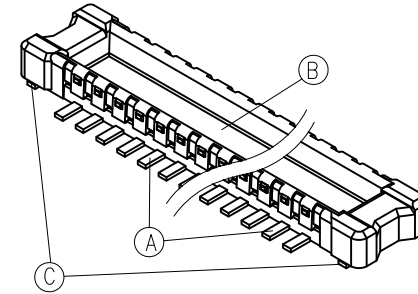
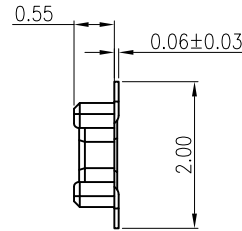
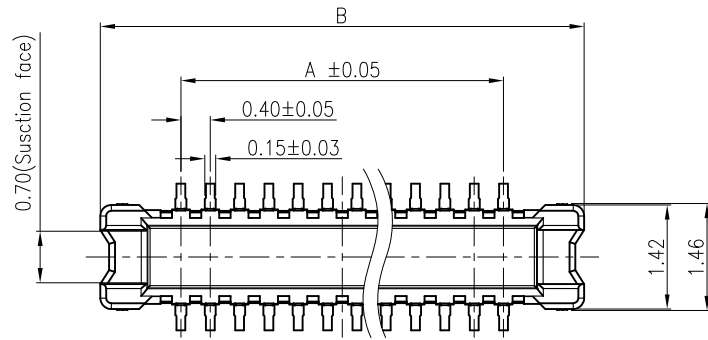


General tolerance		P/N		TITLE		0.4mm Pitch BOARD TO BOARD MATED HIGHT 0.80mm SOCKET CONNECTOR PACKING SPEC.	
DIMENSION	ANGLES	1C051-XX0XX-000					
.X ± 0.35	X° ± 5°	DR.	PHIL	Original Date	2011/9/8	D/N	1C051-XX0XX-000
.XX ± 0.25	X.X° ± 3°	CHK.	JERRY	SCALE	UNIT	REV.	SHEET
.XXX ± 0.15		APPD.	STING	1:1	mm	H	1/1



CUSTOMER

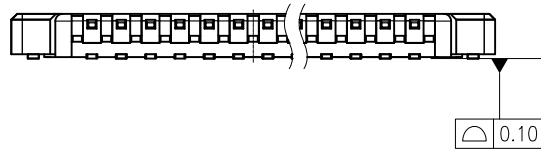
REV.	DCN/ECN	DESCRIPTION	DR.	DATE	APPD.



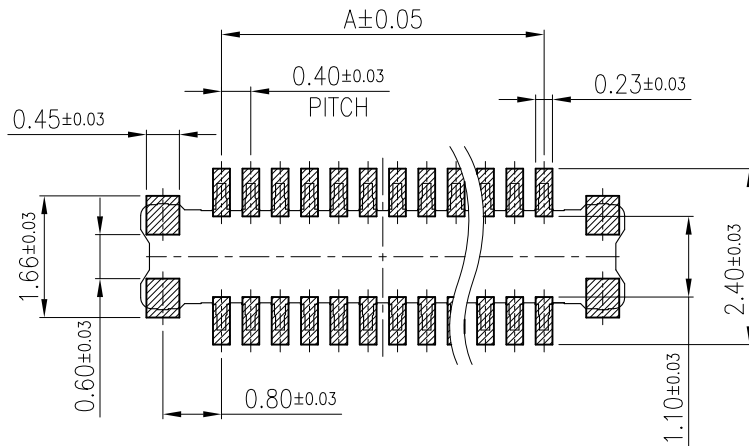
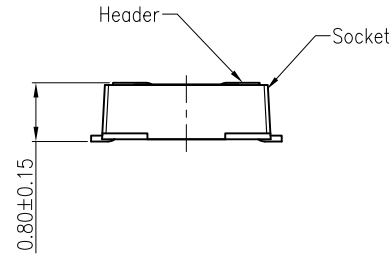
Dimension table (mm)

※ : Mass Production

No. of contacts	Dimension	
	A	B
※ 50	9.60	11.80
※ 60	11.60	13.80
※ 70	13.60	15.80



Matting drawing



Recommended PC board pattern (mounting pad layout)

NOTES :

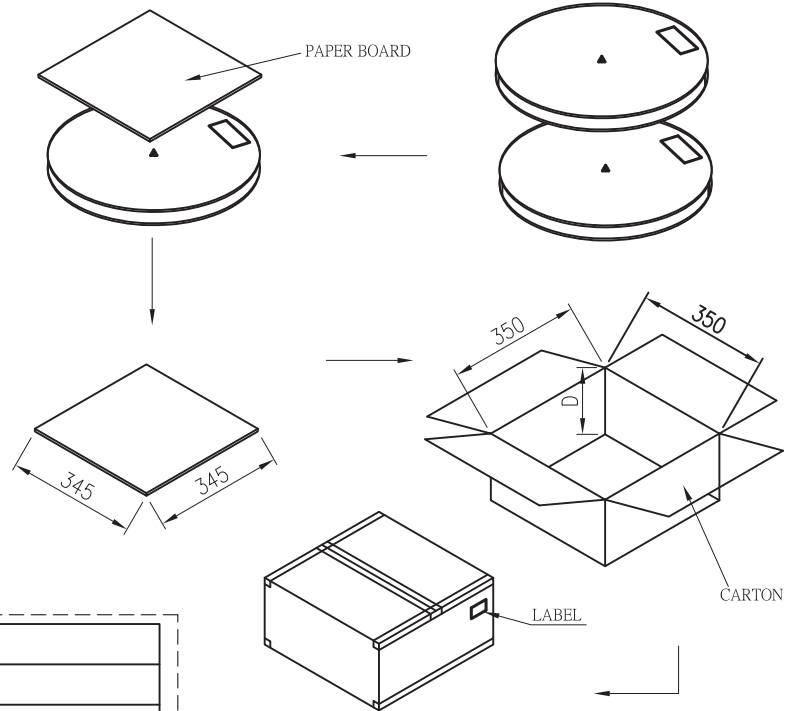
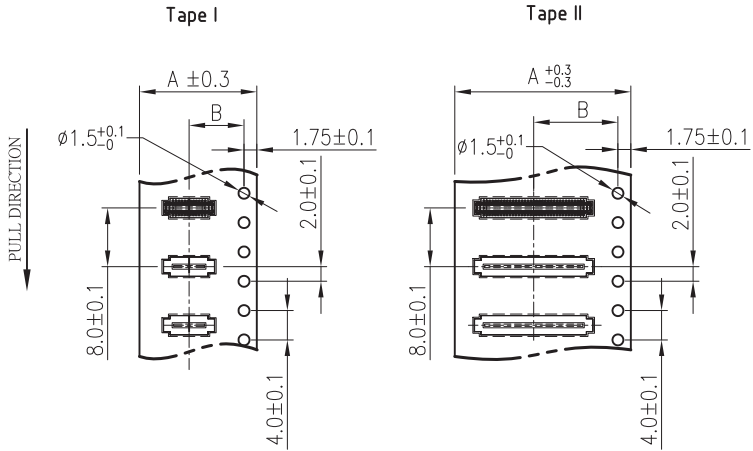
1. Plating : Contact : Contact portion : Au plating (Min. 0.05 μ m) over nickel
Terminal portion : Au plating over nickel

2. Part No. : ASE 6B XX 10

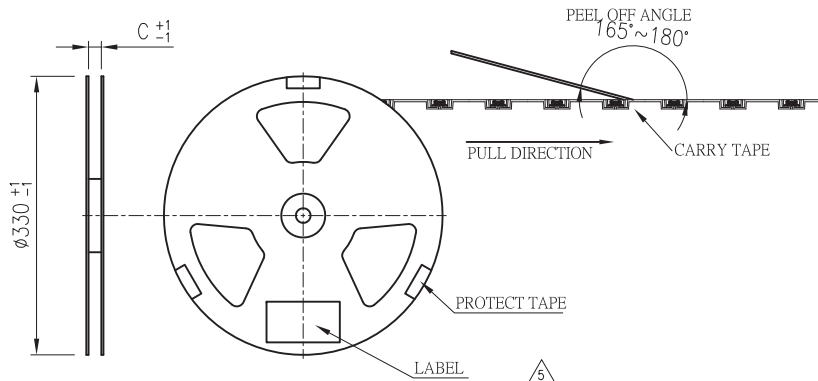
No. OF SERIES 6B : HEADER Contacts No.

③	HOLDDOWN	4	COPPER ALLOY	GOLD	-
②	Housing	1	HIGH TEMP. PLASTIC	BLACK	UL94-V0
①	Terminal	-	COPPER ALLOY	GOLD	-
ITEM	DESCRIPTIONS	QTY.	MATERIAL	FINISH	REMARKS
General tolerance		P/N		TITLE	
DIMENSION		ASE6BXX10		0.4mm Pitch BOARD TO BOARD MATED HEIGHT 0.80mm HEADER CONNECTOR	
ANGLES		Original Date		D/N	
. ± 0.4		2013/10/29		ASE6BXX10	
.X ± 0.3		DR. PHIL		SCALE UNIT REV. SHEET	
.XX ± 0.15		CHK. JERRY		10:1 mm B 1/1	
.XXX ± 0.1		APPD. STING		ATC ASSEM TECHNOLOGY CO., LTD.	

REV.	DCN/ECN	DESCRIPTION	DR.	DATE	APPD.
5	ECN14023	修改上帶預留尺寸	PHIL	2014/08/08	STING
6	ECN15001	修改紙箱高度	PHIL	2015/01/07	STING
7	ECN16014	刪除真空包裝字樣	EASON	2016/09/08	STING



Reel package (EIAJ ET - 7200B) MATERIAL : PS



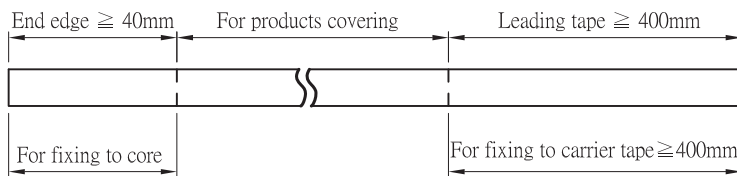
CARTON LABEL

Description	
Part No.	
Quantity	
N. W	
G. W	

REEL LABEL

Assem Technology Co., Ltd	
Description	
Part No.	
Quantity	
Date Code	

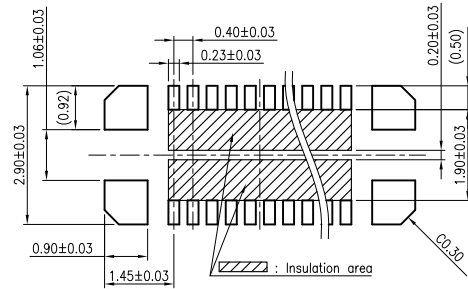
Cover Tape MATERIAL : PET



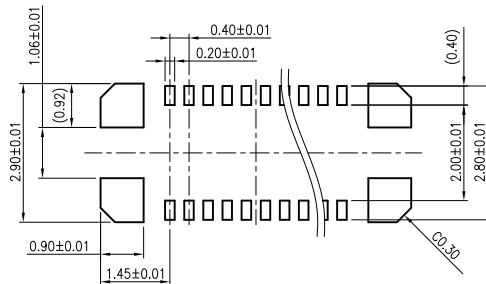
70	ASEM7010								
60	ASEM6010								
50	ASEM5010								
44	ASEM4410								
40	ASEM4010	Tape II	24.0	11.5	25.4		5	25000 pcs 180	
36	ASEM3610								
34	ASEM3410								
30	ASEM3010								
26	ASEM2610								
24	ASEM2410								
22	ASEM2210						5000 pcs		
20	ASEM2010								
18	ASEM1810	Tape I	16.0	7.5	17.4		5	25000 pcs 145	
16	ASEM1610								
14	ASEM1410								
12	ASEM1210								
10	ASEM1010								
PM	P / N	Type of Taping	DIM A	DIM B	DIM C	Reel	Reels	Carton	DIM D

General tolerance		P/N		TITLE		0.4mm Pitch BOARD TO BOARD MATED HIGHT 0.80mm HEADER CONNECTOR PACKING SPEC.			
DIMENSION	ANGLES	1C052-XX0XX-XXX							
.X ± 0.35	X° ± 5°	DR.	PHIL	Original Date	2011/9/8	D/N	1C052-XX0XX-XXX		
.XX ± 0.25	X.X° ± 3°	CHK.	JERRY	SCALE	UNIT	REV.	SHEET		
.XXX ± 0.15		APPD.	STING	1:1	mm	I	1/1	ATC ASSEM TECHNOLOGY CO., LTD.	

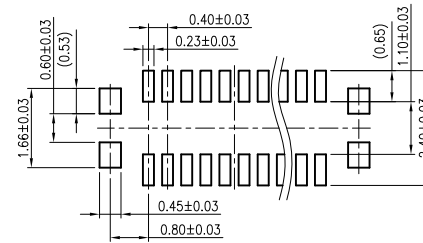
Socket
Recommended PC board pattern
(Mount pad arrangement pattern)



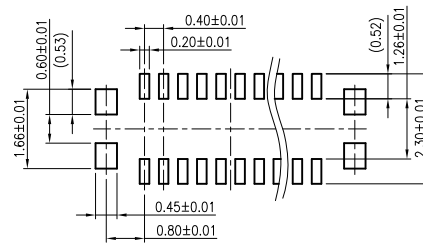
Recommended metal mask pattern
metal mask thickness : Here, 120 μm
(Terminal portion opening area ratio : 70%)
(Metal portion opening area ratio : 100%)



Header
Recommended PC board pattern
(Mount pad arrangement pattern)

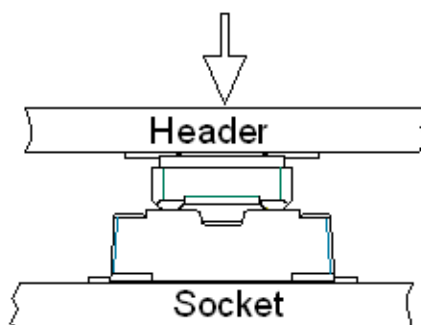
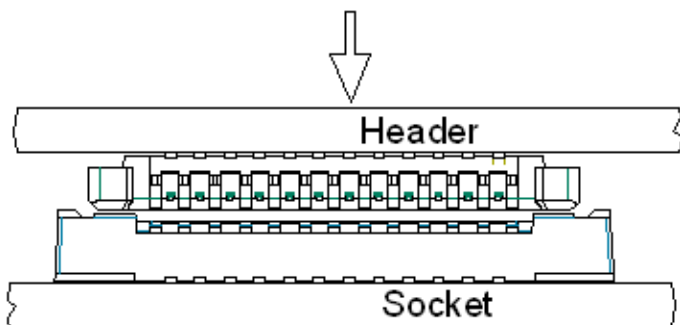


Recommended metal mask pattern
metal mask thickness : Here, 120 μm
(Terminal portion opening area ratio : 70%)
(Metal portion opening area ratio : 100%)

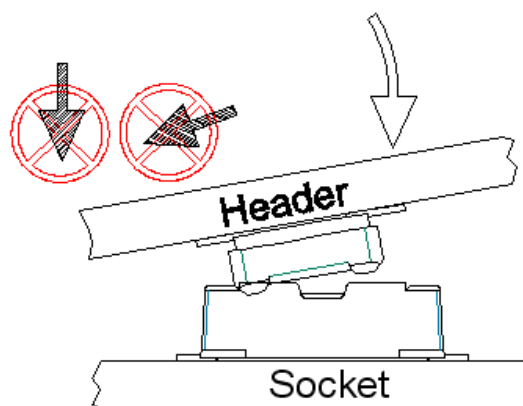
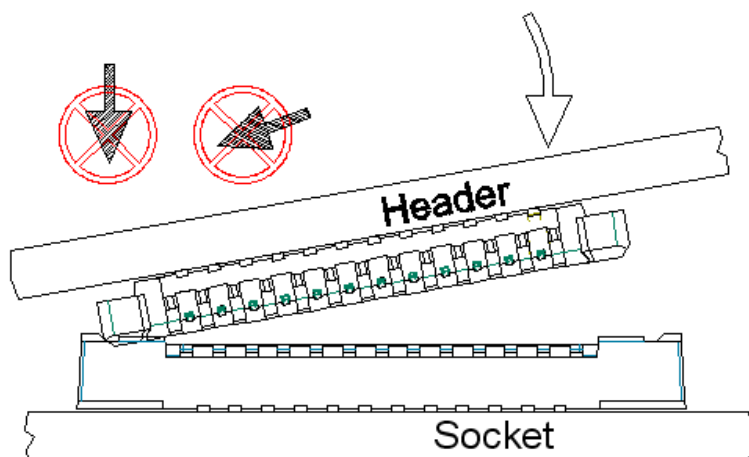


1. 插入方式

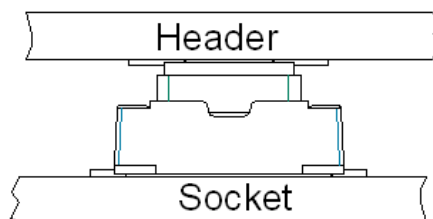
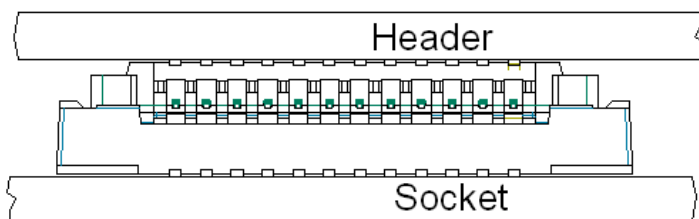
1-1 (1). 將公端保持平行，並輕放至母座之對應搭接槽內。



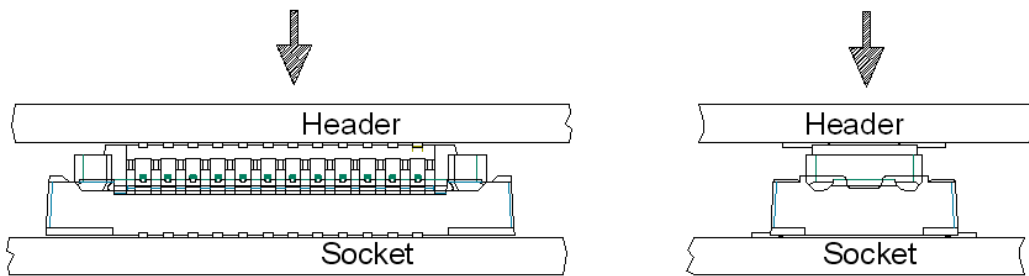
(2). 或者以 $< 20^\circ$ 之斜角進行限位(此過程切勿用力施壓)，再將另一端輕輕放至平行。



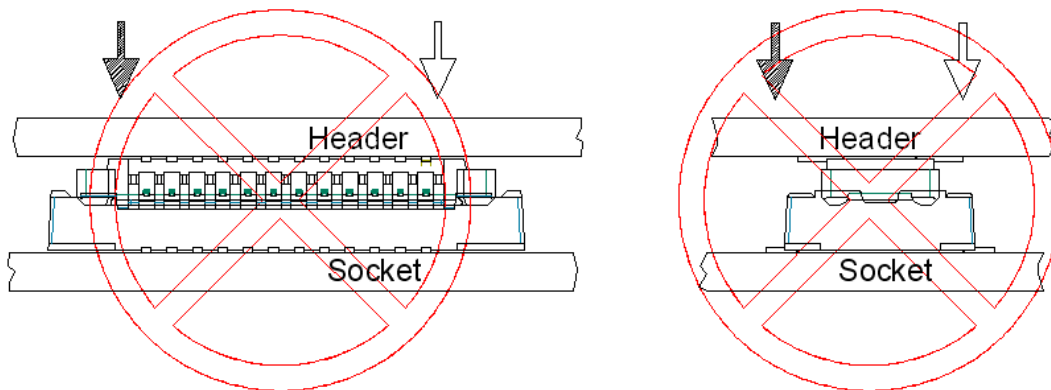
1-2 經過上述對位的步驟，此時公母座產品確實限位，但仍未扣合。



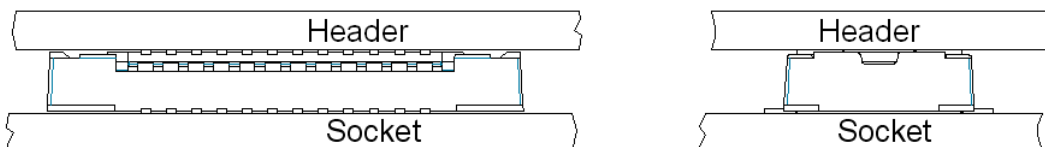
1-3 (1).當對位完成後，請再平均施力及平行壓入，此時會有響聲確認完成扣合。



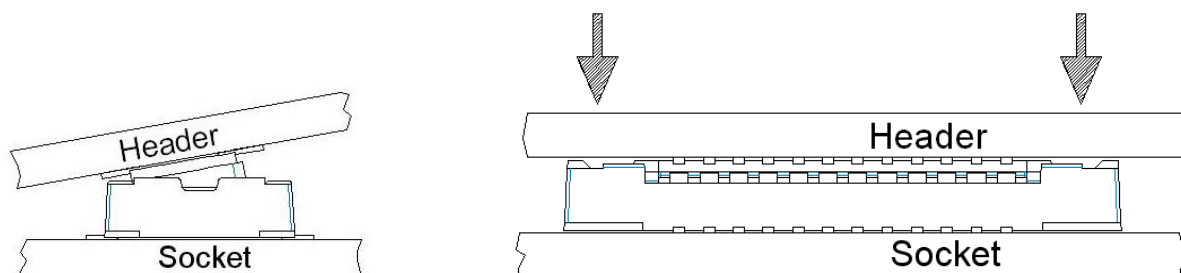
(2).在扣合施力過程中，務請避免兩側施力不均之情形。



(3).當扣合完成後，公母座必須保持平行之狀態。



(4).若在扣合後，公母座未能保持平行(未完全組裝到位)之狀態，請再於長邊二側平均施力壓入，以完成正確之扣合。



1-4 當 1-1、1-2 步驟未能確實完成時，切勿施力扣合，否則將有造成產品破損之風險；當施力下壓無法順利扣合時，請再重新進行對位與扣合作業步驟。

TITLE: 0.4mm Pitch B TO B CONNECTOR

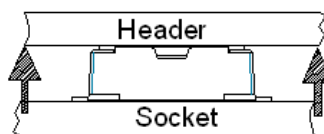
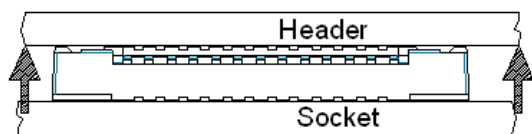
Date : 2014.03.11

REV

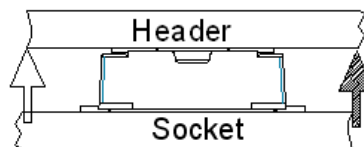
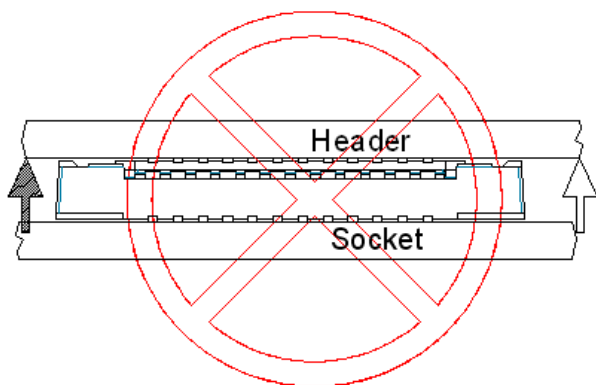
B

2. 拔出方式

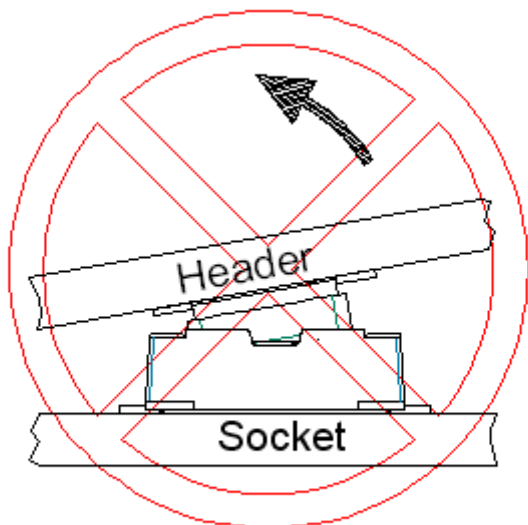
2-1 平均施力平行拔出。



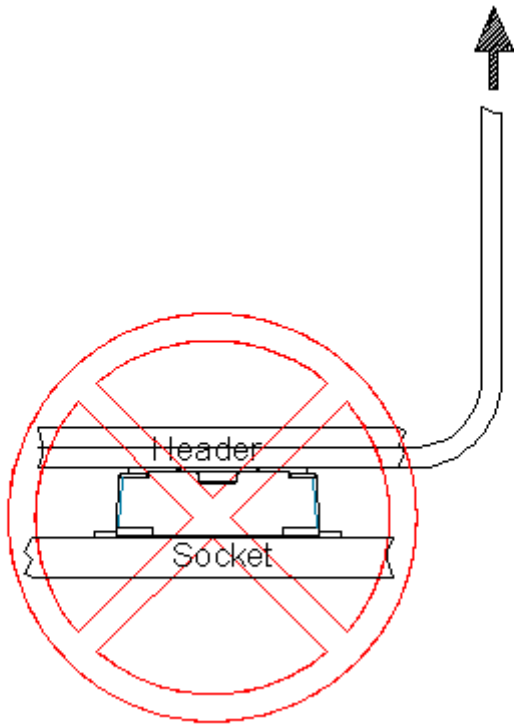
2-2 長邊方向避免單邊拔出，短邊方向可單邊拔出



2-3 單邊拔出後不可繼續旋轉施力



2-4 避免以拉軟性電路板(FPC)方式分離



2-5 避免單一角落單獨施力

